



February 6, 2009

Revision of Forecast for the Fiscal Year Ending March 31, 2009

Company name: TOKYO SEIMITSU CO., LTD.

(Stock code: 7729, Tokyo Stock Exchange 1st Section)

Representative: Sadakatsu Suzuki, Chairman and CEO

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TOKYO SEIMITSU CO., LTD. announced today the revised forecasts for the fiscal year 2009 ending March 31, 2009. Previous forecasts were announced on November 13, 2008.

	Sales	Operating Income	Ordinary Income	Net Income	Net Income per share (yen)
Previous Forecast (A)	53,000	1,500	1,100	-1,600	-39.80
Revised Forecast (B)	45,500	-2,500	-3,000	-12,000	-298.51
Change (B-A)	-7,500	-4,000	-4,100	-10,400	-
Change Ratio (%)	-14.2%	-	-	-	-
Results for the previous term ended March 2008	91,823	10,450	9,375	4,813	119.84

Reason of revision

In line with the severe worldwide recession sparked by the US financial crisis, our company's Semiconductor Production Equipment (SPE) and Metrology businesses have been experiencing difficult conditions. In addition to the weakened market situation, the recent appreciation of the yen has negatively affected our performance. Accordingly, our Sales figures for this year and Operating and Ordinary Income will also be significantly lower than estimates released last November.

In response to these continuing severe business conditions, Company management has decided to implement a rigorous "selection and concentration" strategy in the SPE business and to push forward with more cost reductions across all businesses.

Measures

1) Focus on our core businesses of Wafer Probing Machines in Test processes and on Wafer Dicing Machines and Polish Grinding Machines in Back End Processes. Concentrate more personnel and resources in these areas, accordingly.

- 2) For the Wafer Inspection System Business, our company will discontinue any further development of new systems and limit its resources to providing support for existing machines.
- 3) For the Device Edge Business, our company will suspend any further development and liquidate its subsidiary company, Accretech USA, Inc. which until now has had the carriage of this business.
- 4) Along with a series of SPE business reviews, Company Management has resolved to initiate a voluntary retirement scheme.

As a result, the Company anticipates taking up losses of approximately 4.7 billion yen in relation to the termination of the Wafer Inspection System Business and approximately 2.5 billion yen for liquidation of the USA subsidiary. Additional losses for severance pay and stock evaluation losses, will lead to a total of up to 8.2 billion of special losses for the 2nd half of the financial year. Consequently, Net Income will be revised down to include these special losses in addition to the expected decrease in Ordinary Income.

Cautionary Statements with Respect to Forward-looking Statements

Statements made in this commentary with respect to our plans and benefits as well as other statements that are not historical facts are forward-looking statements, which involve risks and uncertainties. Potential risks and uncertainties include, without limitation, general economic condition in our markets, exchange rates, and our ability to continue to win customers' acceptance of its products, which are offered in highly competitive markets characterized by continual new product introductions and rapid developments in technology.